

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| MASATSUGU SHIGENO | 03/14/2017 |
| KAZUTOSHI WATANABE | 03/14/2017 |
| MASAFUMI WATANABE | 03/14/2017 |
| HIROYOSHI YAMAMOTO | 03/14/2017 |
| KAZUO CHINONE | 03/14/2017 |
| RECEIVING PARTY DATA | |
| Name: | HITACHI HIGH-TECH SCIENCE CORPORATION |
| Street Address: | 24-14, NISHI-SHIMBASHI 1-CHOME, MINATO-KU, |
| City: | TOKYO |
| State/Country: | JAPAN |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 15468668 |
| CORRESPONDENCE DATA | |
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| NAME OF SUBMITTER: | JUSTINA TOWNSEND |
| SIGNATURE: | /Justina Townsend/ |
| DATE SIGNED: | 03/24/2017 |
| Total Attachments: 3 | |
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| source=03133435#page2.tif | |

ASSIGNMENT

WHEREAS, WE,

1. Masatsugu SHIGENO of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan,
2. Kazutoshi WATANABE of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan,
3. Masafumi WATANABE of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan,
4. Hiroyoshi YAMAMOTO of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan,
5. Kazuo CHINONE of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan,

have invented an improvement in SCANNING PROBE MICROSCOPE AND PROBE CONTACT DETECTION METHOD and have executed an application for a United States patent based thereon simultaneously herewith;

AND, WHEREAS, HITACHI HIGH-TECH SCIENCE CORPORATION of 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan, a corporation of Japan (hereinafter referred to as "ASSIGNEE") is desirous of acquiring certain rights thereunder;

NOW, THEREFORE, for one dollar and other good and valuable consideration, receipt of all of which is hereby acknowledged, we have agreed to and do hereby sell, assign and transfer unto said

ASSIGNEE the entire right, title and interest, including the right to claim priority, in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto in and to said invention, said United States application, any other United States applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on said United States application or in whole or in part on said invention, any foreign applications based in whole or in part on any of the aforesaid United States applications or in whole or in part on said invention, and any and all patents (including extensions thereof) of any country which have been or may be granted on any of the aforesaid applications or on said invention or any part thereof;

TO BE HELD AND ENJOYED by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us had no sale and assignment of said interest been made;

AND WE hereby authorize and request the Director of the United States Patent and Trademark Office of the United States of America to issue any and all United States patents which may be granted upon said United States applications or any of them, or upon said invention or any part thereof, to said ASSIGNEE;

AND WE hereby agree for ourselves and for our heirs, executors and administrators, to execute without further consideration any further lawful documents and any further assurances, and any provisional, non-provisional, divisional,

continuing, reissue, or other applications for patents of any country, that may be deemed necessary by said ASSIGNEE fully to secure to said ASSIGNEE its interest as aforesaid in and to said invention or any part thereof, and in and to said several patents or any of them;

AND WE hereby covenant for ourselves and our legal representatives, and agree with said ASSIGNEE, its successors and assigns, that we have granted no right or license to make, use or sell said invention, to anyone except said ASSIGNEE, that prior to the execution of this deed our right, title and interest in said invention had not been otherwise encumbered, and that we have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, we have hereunto set our hands.

14 March, 2017
Date

Masatsugu Shigeno
Masatsugu SHIGENO

14 March, 2017
Date

Kazutoshi Watanabe
Kazutoshi WATANABE

2017.3.14
Date

Masafumi Watanabe
Masafumi WATANABE

2017.3.14
Date

Hiroyoshi Yamamoto
Hiroyoshi YAMAMOTO

14 March, 2017
Date

Kazuo Chinone
Kazuo CHINONE